## In the Claims

Please replace the claims with the following clean version of the entire set of pending claims, in accordance with 37 CFR § 1.121(c)(1)(i). Cancel all previous versions of any pending claim.

A marked-up version showing amendments to any claims being changed is provided in one or more accompanying pages separate from this amendment in accordance with 37 CFR § 1.121(c)(1)(ii). Any claim not accompanied by a marked-up version has not been changed relative to the immediate prior version, except that marked-up versions are not being supplied for any added claim or canceled claim.

## **CLAIMS**

(V) (V)

- 22. (Amended) An integrated circuit package separator for separating a plurality of integrated circuit packages from one another, the integrated circuit packages being provided as integrated circuit chip components joined to a board, the separating including cutting the board, the separator comprising:
  - a panel;
- a plurality of blocks over the panel, the blocks having curved upper surfaces and being configured to support the board while leaving the integrated circuit chip components extending between the block upper surfaces and the panel;
- a cutting mechanism configured to cut the board while the board is supported on the blocks and to thereby separate the integrated circuit packages from one another; and

wherein the panel is immobile relative the plurality of the blocks.

- 31. The separator of claim 22 further comprising pins extending upwardly from beneath the panel to beyond an upper surface of the panel, the pins configured to extend into the board and retain the board over the panel.
- 32. The separator of claim 31 wherein the pins do not extend through the panel.

- 33. The separator of claim 31 further comprising an actuator beneath the panel and configured to vertically displace the panel.
- 34. The separator of claim 33 wherein the actuator is pneumatically powered.
- 92. The separator of claim 22 further comprising an actuator beneath the panel and configured to vertically displace the panel.
- 93. The separator of claim 22 further comprising a pneumatically-powered actuator beneath the panel and configured to vertically displace the panel.

Please cancel claims 94-99.

100. The separator of claim 22 further comprising pins extending upwardly from beneath the panel to beyond an upper surface of the panel, the pins configured to extend into the board and retain, the board spaced from the panel.

## Please add the following new claims:

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101. (New) The separator of claim 22 wherein the panel comprises

aluminum.

102. (New) The separator of claim 22 wherein the blocks are formed as one piece with the panel.

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103. (New) The separator of claim 22 wherein the blocks are formed as discrete pieces from the panel.

104. (New) The separator of claim 22 wherein the blocks are formed as discrete pieces from the panel and are fastened to the panel.

an uppermost surface of the panel at a height from about 0.035 inches to about 0.045 inches.

106. (New) The separator of claim 22 wherein the blocks extend above an uppermost surface of the panel at a height from about 0.135 inches to about 0.145 inches.

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- 107. (New) The separator of claim 22 wherein the panel is secured to the separator by screws.
- 108. (New) The separator of claim 22 wherein the panel is secured to the separator by rivets.
- 109. (New) The separator of claim 22 wherein the panel is molded as part of the separator.

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110. (New) An integrated circuit package separator for separating a plurality of integrated circuit packages from one another, the integrated circuit packages being provided as integrated circuit chip components joined to a board, the separating including cutting the board, the separator comprising:

a panel having an uppermost surface and molded as part of the separator;

a plurality of blocks formed as one piece with the panel and extending upward from the uppermost surface of the panel to support the board leaving the integrated circuit chip components extending between the blocks and panel; and

a cutting mechanism configured to cut the board while the board is supported on the blocks and to thereby separate the integrated circuit packages from one another.

- 111. (New) The separator of claim 110 wherein the panel comprises aluminum.
- 112. (New) The separator of claim 110 further comprising an actuator beneath the panel and configured to vertically displace the panel.